CLAIMS

1. A signal transmission plate used in an assembly package having a die, a plurality of conductive wires, and a substrate, the signal transmission plate comprising:

at least one insulating layer;

at least one layout wire layer formed on the insulating layer; and

a solder mask layer formed on the layout wire layer, wherein

the solder mask layer exposes partial area of the layout wire layer at the center and peripheries of the signal transmission plate to form a plurality of die bonding pads and a plurality of wire bonding pads.

2. The signal transmission plate as claimed in claim 1, wherein the die is electrically connected with the die bonding pads, the wire bonding pads are electrically connected with the substrate via the conductive wires.

3. The signal transmission plate as claimed in claim 1, wherein the layout wire layer is formed by patterning a metal foil.

4. The signal transmission plate as claimed in claim 1, wherein the metal foil is a copper foil.

5. The signal transmission plate as claimed in claim 1, wherein the insulating layer is formed of bismaleimide triazine (BT).

6. The signal transmission plate as claimed in claim 1, wherein the insulating layer is formed of glass epoxy.